



SMD Comm X8G HT150C Flex, Ceramic, 68 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1210	
L	3.3mm +/-0.4mm	
W	2.6mm +/-0.3mm	
Т	0.78mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	
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S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	

	Specifications		
	Capacitance	68 pF	
	Measurement Condition	1 MHz 1.0Vrms	
	Tolerance	10%	
	Voltage DC	200 VDC	
	Dielectric Withstanding Voltage	500 VDC	
	Temperature Range	-55/+150°C	
	Temp. Coefficient	X8G	
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
	Dissipation Factor	0.1% 1 MHz 1.0Vrms	
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
	Insulation Resistance	100 GOhms	

Packaging	T&R, 330mm, Plastic Tape	Applied (TCC)
Packaging Quantity	10000	Dissipation Factor
		Aging Rate

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